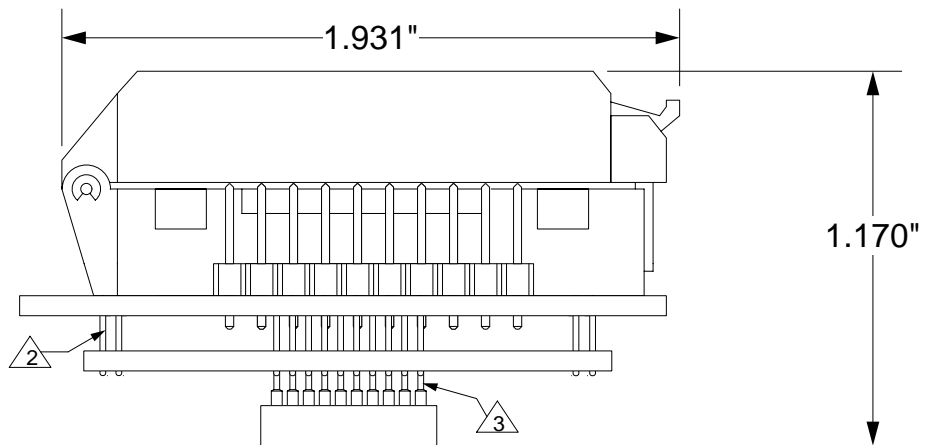


Top View




Side View

- 1 Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- 2 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- 3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.). Contact material- BeCu; finish 10µ" Au over 100µ" Ni (min.)

Description: Carrier Adaptor  
 100 position (0.65mm pitch) QFP Zero Insertion Force socket with test points to 100 position Mini-grid socket interface.

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.

<b>CA-QFE100RE-M-Z-01 Drawing</b>		Status: Released	Scale 3:2	Rev: A
 <p>© 2008 IRONWOOD ELECTRONICS, INC.          11351 Rupp Dr. Suite 400, Burnsville MN          Tele: (952) 229-8200          www.ironwoodelectronics.com</p>	Drawing: E Smolentseva		Date: 05/27/08	
	File:CA-QFE100RE-M-Z-01 Dwg		Modified:	